

AMENDMENT**Amendments to the Claims**

This listing of claims replaces all prior versions and listings of claims in the subject application:

Listing of Claims:

1. (Currently Amended) An electronics component mounting system, comprising:
a first mounting structure including:
two generally parallel and opposing spacers configured to space a first electronics component to be mounted to the first mounting structure from an electronics base, the first mounting structure being configured to be attached to the electronics base;
a plurality of supports extending from the spacers, the supports being configured to engage holes defined on a surface of ~~[[a]]~~ the first electronics component ~~to be mounted on the first mounting structure;~~ and
a base portion extending between the two generally parallel and opposing spacers, the spacers and the supports being generally orthogonal to the base portion.
2. (Original) The system of claim 1, wherein each spacer defines an orifice configured to allow a fastening mechanism to pass therethrough and engage thereto.
3. (Original) The system of claim 1, further comprising a fastening mechanism to secure the first mounting structure to the first electronics component.
4. (Original) The system of claim 3, wherein the fastening mechanism comprises a hook and loop material.
5. (Original) The system of claim 1, wherein the supports are tapered so that the supports decrease in size as the supports extend away from the spacers.
6. (Original) The system of claim 5, wherein the supports are made of a material that is harder than the material of the holes defined on the surface of the first electronics component.

7. (Currently Amended) The system of claim 1, further comprising:
[[an]] the electronics base, the first mounting structure being rigidly attached to the electronics base, the first mounting structure and the electronics base being separately formed.
8. (Currently Amended) The system of claim 1, further comprising:
[[an]] the electronics base, the first mounting structure being integrally formed
[[from]] with the electronics base.
9. (Original) The system of claim 1, wherein the base portion extending between the spacers includes a plurality of sharp points configured to face and be secured to a surface of a second electronics component onto which the first mounting structure and the first electronics component are stacked.
10. (Original) The system of claim 9, further comprising angled legs extending from the spacers and opposing the sharp points, the angled legs having an angled surface to engage the second electronics component.
11. (Original) The system of claim 9, further comprising:
a second mounting structure including:
two generally parallel and opposing second spacers;
a plurality of second supports extending from the second spacers, the second supports being configured to engage holes defined on a surface of the second electronics component to be mounted on the second mounting structure,
a second base portion extending between the two generally parallel and opposing second spacers, the second spacers and the second supports being generally orthogonal to the second base portion.
12. (Original) The system of claim 1, further comprising:
a second mounting structure including:
two generally parallel and opposing second spacers;

a plurality of second supports extending from the second spacers, the second supports being configured to engage holes defined on a surface of a second electronics component to be mounted on the second mounting structure,

a second base portion extending between the two generally parallel and opposing second spacers, the second spacers and the second supports being generally orthogonal to the second base portion, the second mounting structure being configured to be mounted to the first electronics component.

13. (Currently Amended) An electronics component mounting apparatus, comprising: component mounting means for securing a first electronics component to an electronics base, including:

means for spacing the first electronics component from the electronics base; the spacing means being configured to space the first electronics component to be mounted on the component mounting means from the electronics base, the component mounting means being configured to be attached to the electronics base; [[, and]]

means for engaging a plurality of holes defined on a surface of the first electronics component to be mounted on the mounting mechanism, said means for engaging extends from said means for spacing; and

means for securing the component mounting means to the first electronics component.

14. (Original) The apparatus of claim 13, wherein said means for spacing defines a means for allowing a fastening mechanism to engage thereto.

15. (Original) The apparatus of claim 13, wherein said means for engaging includes means for engaging holes defined on the surface of the first electronics component to be mounted on said component mounting means.

16. (Original) The apparatus of claim 13, further comprising means for biting into a surface of a second electronics component onto which the component mounting means and the first electronics component are stacked.

17. (Currently Amended) A method, comprising the steps of:

positioning a first electronics component onto opposing spacers of a first mounting structure, the spacers being configured to space the first electronics component to be mounted to the first mounting structure from an electronics base, the first mounting structure being configured to be attached to the electronics base;

engaging a plurality of supports extending from the spacers with holes defined on a surface of the first electronics component; and

securing the first electronics component and the first mounting structure to each other.

18. (Original) The method of claim 17, wherein the step of securing includes the step of engaging a fastening mechanism to orifices defined in the opposing spacers of the first mounting structure.

19. (Original) The method of claim 17, wherein the step of engaging includes the step of engaging the spacers with holes defined on the surface of the first electronics component.

20. (Original) The method of claim 17, further comprising the steps of:

securing a plurality of sharp points of a member connecting the opposing spacers to a surface of a second electronics component onto which the first mounting structure and the first electronics component are to be stacked.

21. (Original) The method of claim 20, further comprising the step of resting angled legs extending from the opposing spacers and opposite the sharp points onto the second electronics component.

22. (Original) The method of claim 20, further comprising the steps of positioning the second electronics component onto opposing spacers of a second mounting structure;

engaging a plurality of second supports extending from the second spacers of the second mounting structure with second holes defined on a second surface of the second electronics component, wherein the step of securing includes securing the second electronics component to the first electronics component and the first mounting structure.